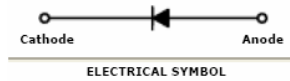
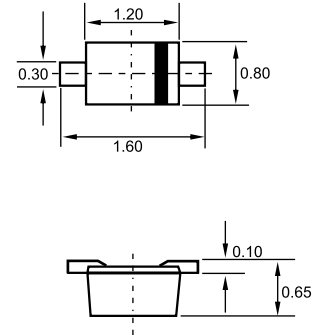


Features

- Low Forward Voltage Drop
- Flat Lead, Surface Mount Device at 0.60mm Height
- Extremely Small Outline Plastic Package SOD523
- Moisture Level Sensitivity 1
- Pb-free Version and RoHS Compliant
- Matte Tin (Sn) Lead Finish
- Green Mold Compound

SOD-523



Dimensions in inches and (millimeters)

Absolute Maximum Ratings* Ta=25qC unless otherwise noted

Symbol	Parameter	Value	Units
V_{RRM}	Maximum Repetitive Reverse Voltage	30	V
$I_{F(AV)}$	Average Rectified Forward Current	200	mA
T_J	Operating Junction Temperature Range	-55 to +125	°C
T_{STG}	Storage Temperature Range	-55 to +125	°C

* These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

Thermal Characteristics

Symbol	Parameter	Value	Unit
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	500	°C/W
P_D	Total Device Dissipation(TC=25°C)	200	mW

*Device mounted on FR-4 PCB minimum land pad.

Electrical Characteristics* Ta=25qC unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
B_{VR}	Breakdown Voltage	$I_R = 500 \mu A$	30			V
I_R	Reverse Current	$V_R = 10 V$			1	μA
V_F	Forward Voltage	$I_F = 200 mA$			0.6	V

Typical Performance Characteristics

